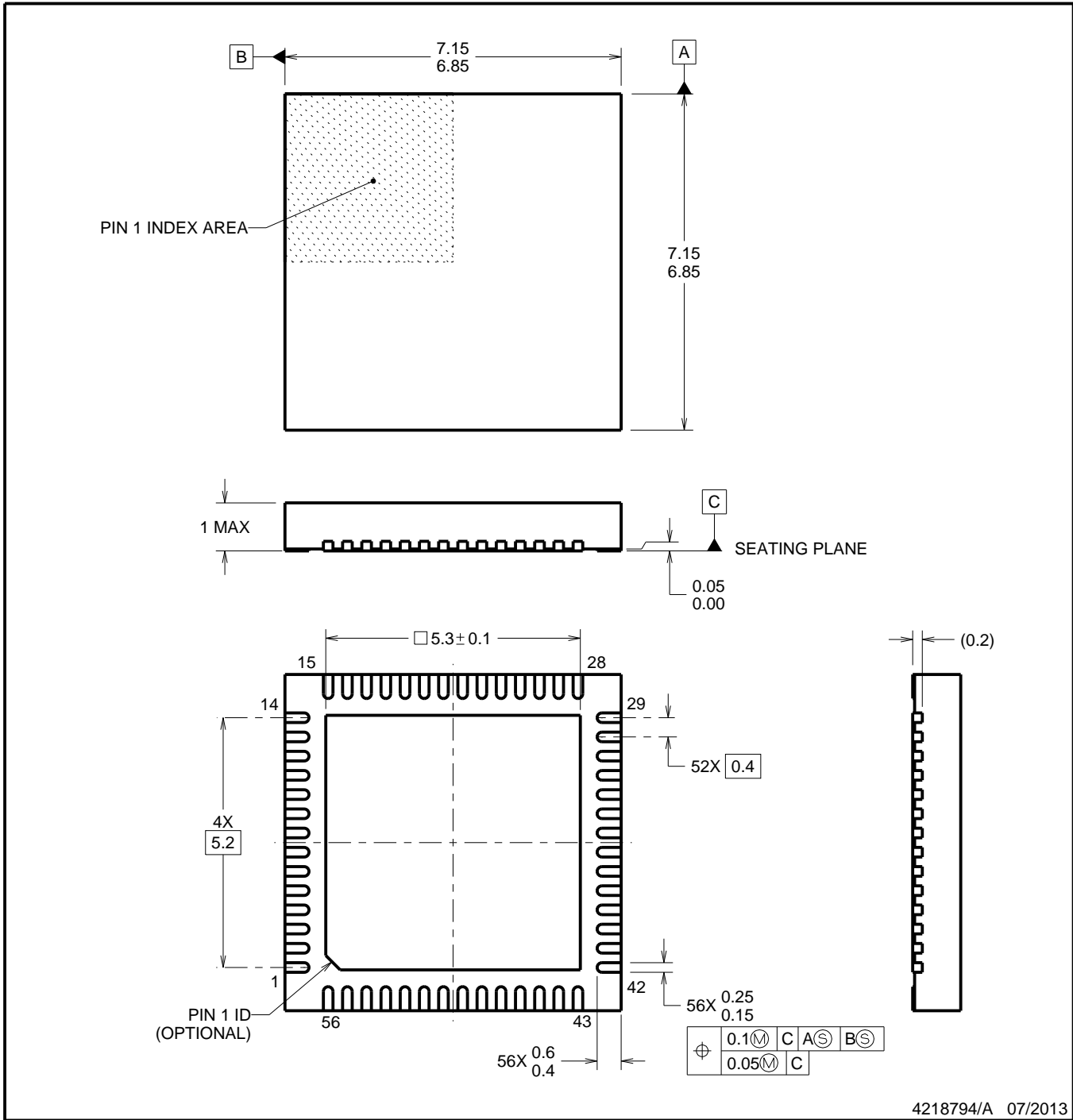


RSH0056D

VQFN - 1 mm max height

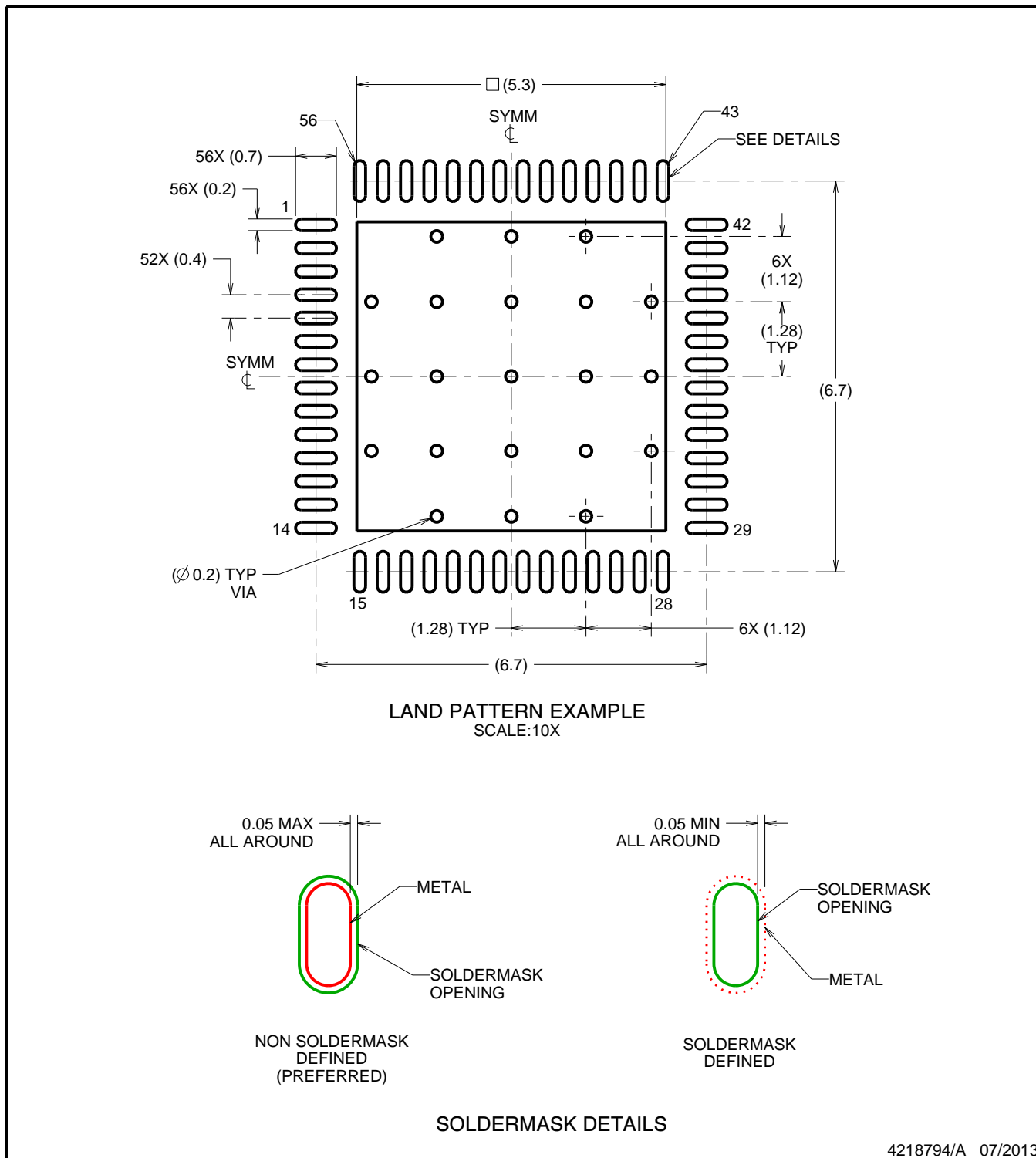
VQFN



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NOTES:

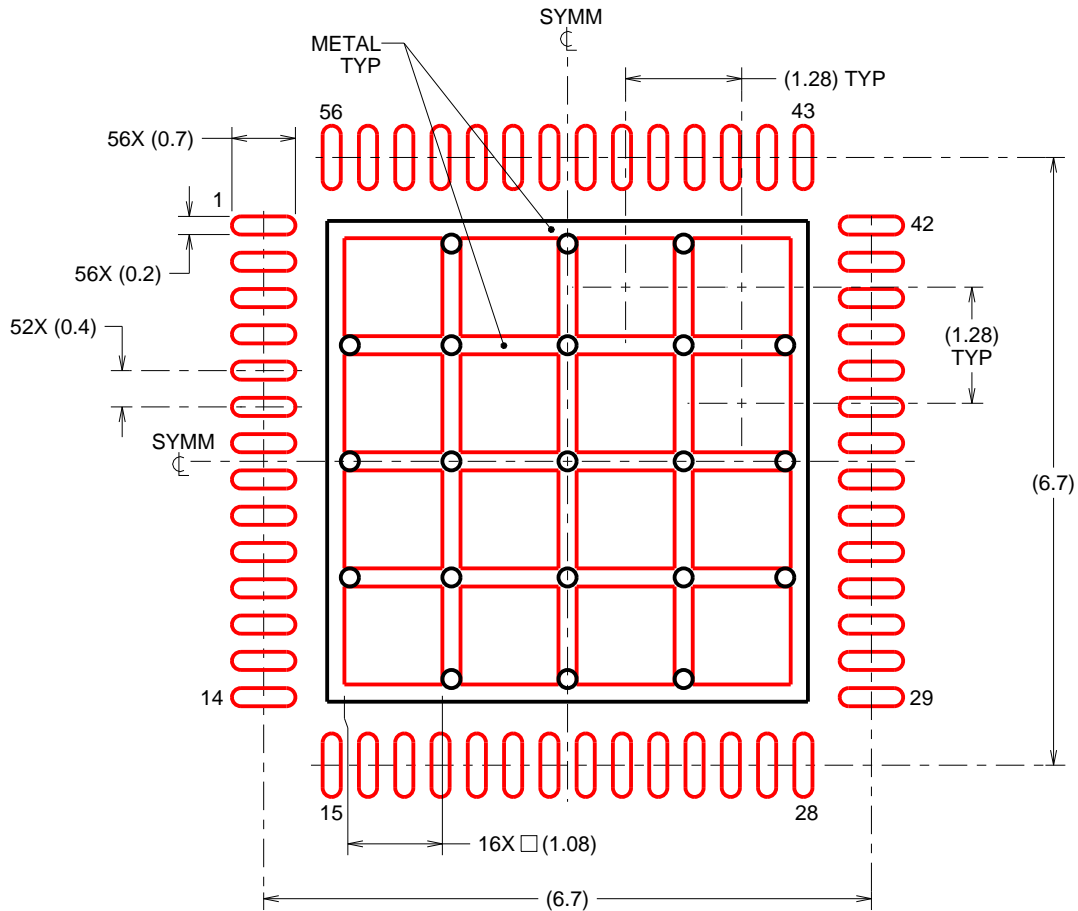
- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



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NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, refer to QFN/SON PCB application note in literature No. SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).



**SOLDERPASTE EXAMPLE**  
 BASED ON 0.1mm THICK STENCIL  
 EXPOSED PAD  
 67% PRINTED SOLDER COVERAGE BY AREA  
 SCALE:12X

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NOTES: (continued)

- 5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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